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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar et al.

Title: APPARATUS AND METHOD FOR PRINTING MICRO METAL STRUCTURES

Docket No.: 1303.096US1

Serial No.: 10/602322

Filed: June 24, 2003

Due Date: N/A

Examiner: Unknown

Group Art Unit: 1763

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.
 An Information Disclosure Statement (2 pgs.), Form 1449 (2 pgs.), and copies of 17 cited documents.

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

By: 
Atty: David C. Peterson
Reg. No. 47,857

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 07 day of September, 2004.

Amelia M. Lester
Name

Amelia M. Lester
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

S/N 10/602322



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar et al. Examiner: Unknown
Serial No.: 10/602322 Group Art Unit: 1763
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INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No :10/602322

Filing Date: June 24, 2003

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Dkt: 1303.096US1

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

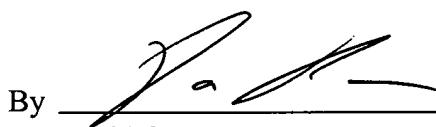
Respectfully submitted,

PAUL A. FARRAR ET AL.

By their Representatives,

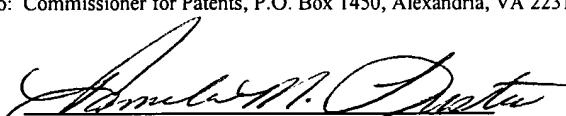
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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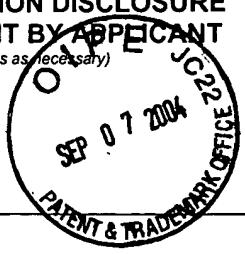
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Name


Signature

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <small>(Use as many sheets as necessary)</small>		Complete if Known Application Number 10/602322 Filing Date June 24, 2003 First Named Inventor Farrar, Paul Group Art Unit 1763 Examiner Name Unknown	
		Attorney Docket No: 1303.096US1	
Sheet 1 of 1			

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
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	US2002/0034581	03/21/2002	Farrar, Paul A., et al.	427	58	02/20/2001
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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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		BABIARZ, A.J., "Key Process Controls for Underfilling Flip Chips", <u>Solid State Technology</u> , 40(4), (April 1997),77-8, 81, 83	
		JONES, P , et al., "Bumped Wafers, Worth Their Weight in Gold?", <u>Advanced Packaging</u> , 8(1), (January 1997),54-57	
		MARCOTTE, V. C., "Review of Flip Chip Bonding", <u>Proceedings of the 2nd ASM International Electronic Materials and Processing Congress</u> , 24-28 April 1989, Philadelphia, PA, (1989),73-81	
		MINGES, MERRILL , "Electronic Materials Handbook", <u>Materials Park, OH : ASM International</u> , (1989),301, 440	
		PUTTLITZ, KARL J., et al., "Solder Transfer Technique for Flip-Chip and Electronic Assembly Applications", <u>IEEE Transactions on Components, Packaging and Manufacturing Technology, Part C</u> , Volume 21, No. 3, (July 1998),182-188	
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EXAMINER

DATE CONSIDERED